

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc2057hdd#trpbf

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

(printed on: 2020-07-11 16:47:34)

TOTAL MASS (g) : 0.022912

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001240 | 1000000 | 54119.2265625 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.009350 | 975000 | 408076.40625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000230 | 24000 | 10038.2431641 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000003 | 300 | 130.933609009 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000007 | 700 | 305.511749268 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.009590 | 1000000 | 418551.09375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000437 | 1000000 | 19089.046875 | | |
| | | External Plating Total: | | | | 0.000437 | 1000000 | 19089.046875 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000218 | 1000000 | 9514.50878906 | | |
| | | Internal Plating Total: | | | | 0.000218 | 1000000 | 9514.50878906 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000656 | 750000 | 28630.8164062 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000219 | 250000 | 9558.15332031 | | |
| Die Attach Total: | | | | 0.000875 | 1000000 | 38188.9726562 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001368 | 130000 | 59705.7265625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.009047 | 860000 | 394852.09375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000105 | 10000 | 4582.67626953 | | |
| | | Encapsulation Total: | | | | 0.010520 | 1000000 | 459140.5 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000032 | 1000000 | 1396.62524414 | | |
| | | | | | TOTAL MASS (g) : | 0.022912 | | |